

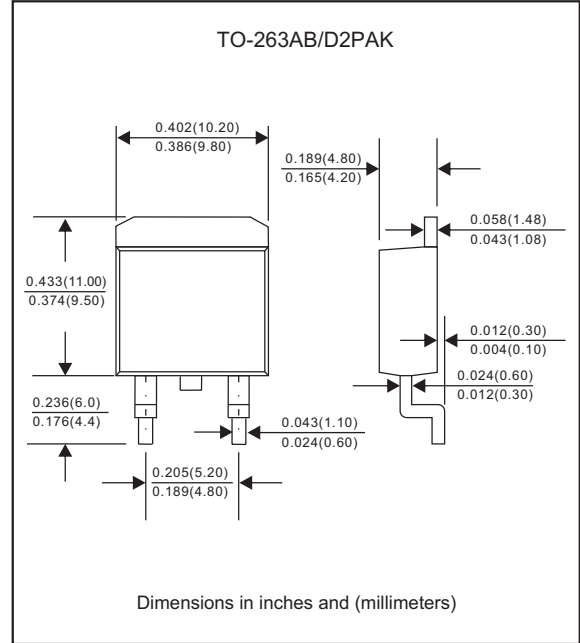
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-263AB / D2PAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	$I_O$			30.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			200	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^\circ\text{C}$	$I_R$			0.1	mA
	$V_R = V_{RRM}$ $T_J = 125^\circ\text{C}$				20	
Thermal resistance	Junction to case	$R_{\theta JC}$		1.4		$^\circ\text{C}/\text{W}$
Storage temperature		$T_{STG}$	-65		+175	$^\circ\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ ( $^\circ\text{C}$ )
MBR3040CG	40	28	40	0.70	-55 to +150
MBR3045CG	45	31.5	45		
MBR3050CG	50	35	50	0.80	
MBR3060CG	60	42	60		
MBR3080CG	80	56	80	0.85	
MBR30100CG	100	70	100		
MBR30150CG	150	105	150	0.92	-55 to +175
MBR30200CG	200	140	200		

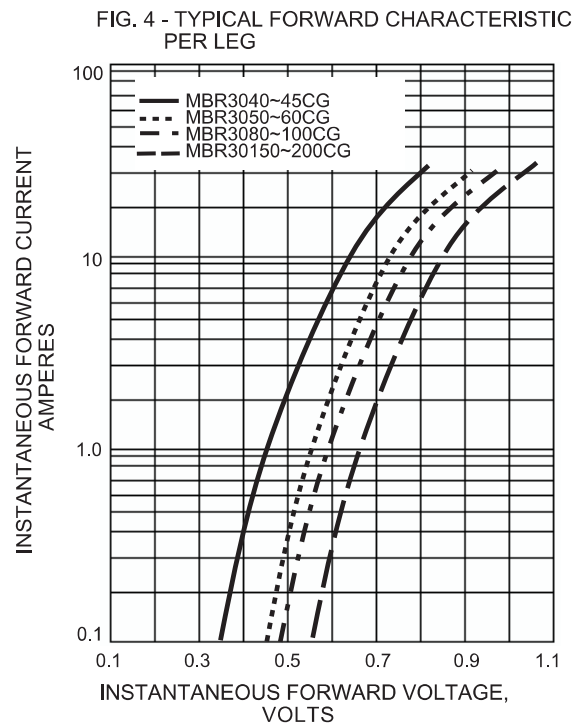
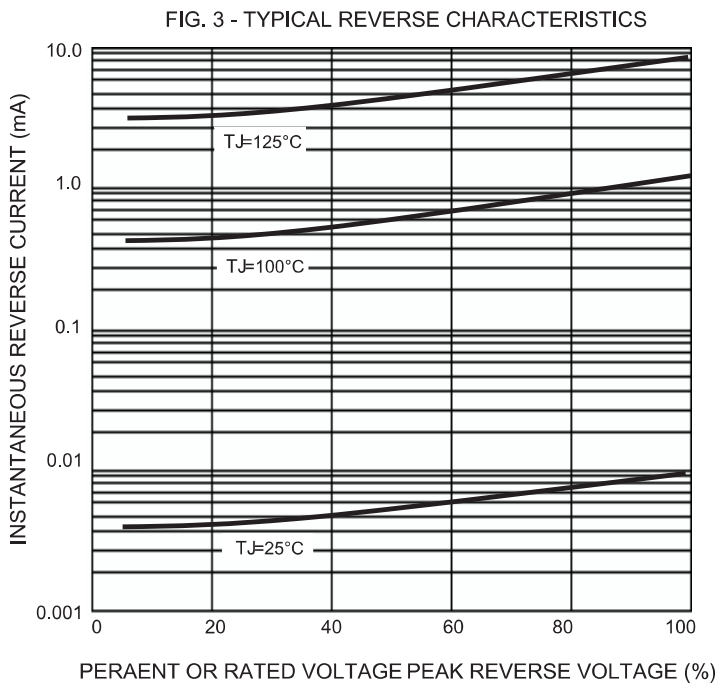
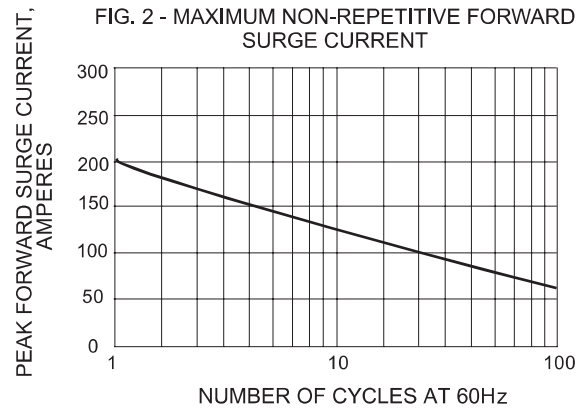
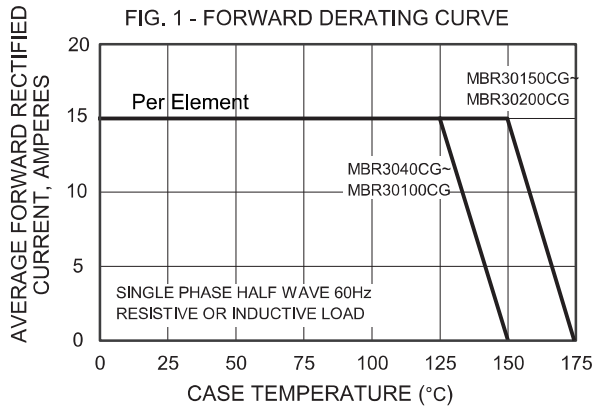
\*1 Repetitive peak reverse voltage

\*2 RMS voltage

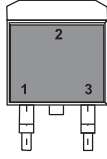
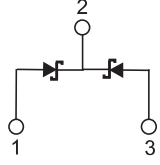
\*3 Continuous reverse voltage

\*4 Maximum forward voltage  
 $I_F = 15.0\text{A}$ ,  $25^\circ\text{C}$

## Rating and characteristic curves (MBR3040CG THRU MBR30200CG)



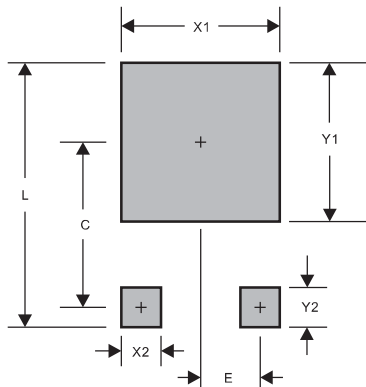
### Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2 cathode Pin3 anode		

### Marking

Type number	Marking code
MBR3040CG	MBR3040CG
MBR3045CG	MBR3045CG
MBR3050CG	MBR3050CG
MBR3060CG	MBR3060CG
MBR3080CG	MBR3080CG
MBR30100CG	MBR30100CG
MBR30150CG	MBR30150CG
MBR30200CG	MBR30200CG

### Suggested solder pad layout



PACKAGE	D2PAK
C	0.374(9.50)
E	0.098(2.50)
L	0.665(16.90)
X1	0.425(10.80)
X2	0.071(1.80)
Y1	0.449(11.40)
Y2	0.138(3.50)

Dimensions in inches and (millimeters)